

ABSTRACT

The present invention provides a heat sink for cooling a component. The component may be one of several components on a circuit board. The heat sink includes a tubular body and a plurality of internal fins. The tubular body has an interior surface and an exterior surface. At least a portion of the exterior surface being substantially flat. The plurality of internal fins extend from the interior surface and are generally symmetric around a center line of the tubular body. The substantially flat portion of the tubular body contacts the component to remove heat from the component. The heat sink may further include a plurality of exterior fins extending from the exterior surface of the tubular body.